National Aeronautics and Space Administration

Advancing SpaceVPX Interoperability

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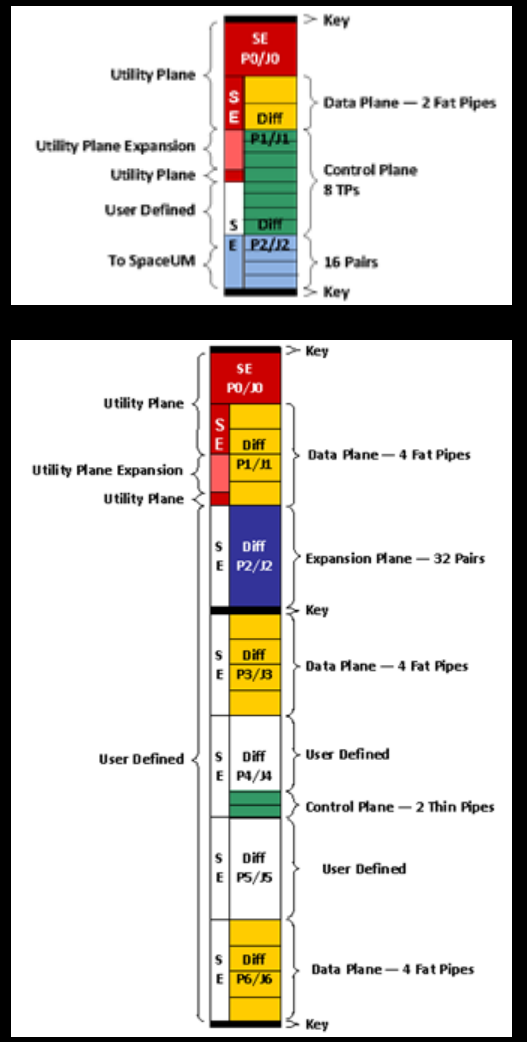
NASA and SpaceVPX

- As NASA exploration moves beyond low-Earth-orbit (LEO), the need for interoperable avionics systems becomes more important due to the cost, complexity, and the need to maintain distant systems for long durations
- The previous NASA-developed and widely adopted standard for backplane-based chassis interconnect, cPCI is over 20 years old and no longer supports modern architectures. cPCI has fallen by the wayside and no other standard has risen to replace it
- Stacked-card avionics, including MUSTANG, have arisen that address applications that require limited bandwidth communication between modules
- However, no standard architecture supporting high-bandwidth, tightly coupled modules, has emerged, resulting in ad hoc, non-optimal box level avionics, with attendant impact on cost, risk, schedule

- The existing SpaceVPX industry standard, as specified in VITA-78, addresses some of the needs of the space avionics community, but falls short of an interoperability standard that would enable reuse and common sparing on long duration missions and reduce NRE for missions in general



3U and 6U Slot Profiles [VITA-78]

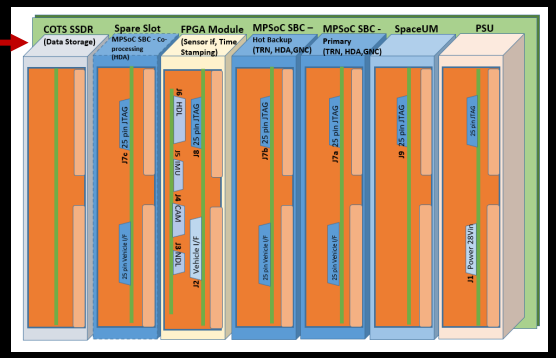
SpaceVPX Overview

SpaceVPX is an architecture standard that defines modules, backplanes, and chassis for spaceflight avionics boxes (the SpaceVPX standard is managed by VMEbus International Trade Association (VITA) as VITA-78)

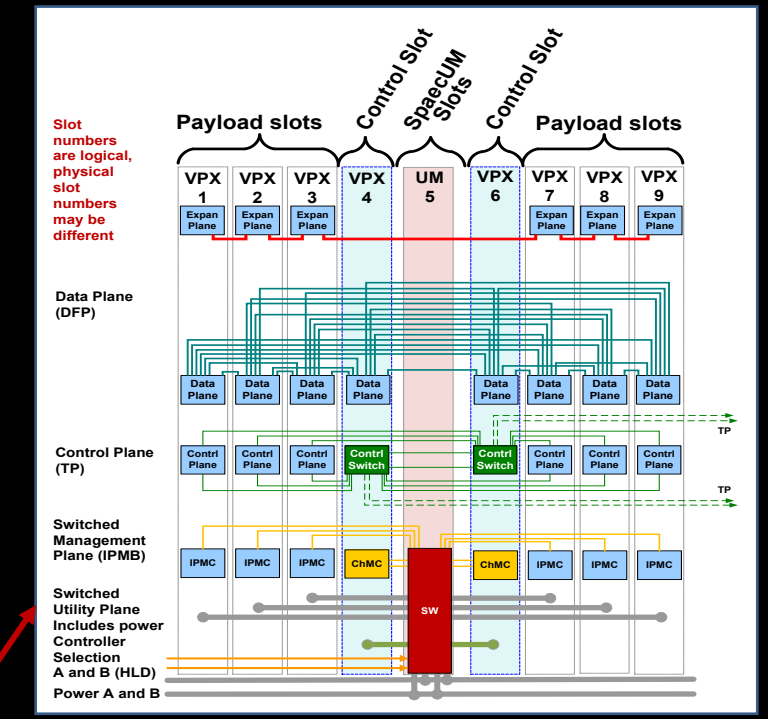
SpaceVPX adapts a Modular Open System Approach (MOSA), derived from VPX and OpenVPX (VITA-65), for space

SpaceVPX defines several general module types and how they can be interconnected, using the concept of "profiles"

- Slot Profile – A physical mapping of ports onto a slot's backplane connectors
- Module Profile - Extends a slot profile by mapping protocols to a module's ports and defines physical dimensions
- Backplane Profile - Defines number and types of modules supported and their interconnection topology



Profile Name	Data Plane 4 FP	Expansion Plane P2/J2	Control Plane 2 TP	User Defined
	DP01 to DP04		CPtp01 to CPtp02	P3/J3, P5/J5
MOD6-PAY-4F1Q2T-12.2.1-1-cc	sRIO 2.2 at 3.125 Gbaud per Section 5.2	sRIO 2.1 at 3.125 Gbaud per Section 5.2	SpaceWire per Section 5.2.1	User Defined DIFF pins



[VITA-78]

SpaceVPX Challenges

It is possible to implement two different modules that are fully compliant with SpaceVPX yet cannot interoperate

- Modules with different form factor and depth complicate chassis implementation
- Even modules with identical slot profiles will not talk to each other if one uses SpaceWire and the other SRIO for data plane network protocols

The immense flexibility of SpaceVPX can limit interoperability

- The standard defines modules with widely varying physical dimensions
  - Form factor (3U and 6U)
  - 4 options for module length
- **There are 48 separate slot profiles defined (not including variations in length and pitch)**
- SpaceVPX does not specify a single network protocols for the control and data planes
  - Possible options include SpaceWire, SpaceFibre, Serial RapidIO (SRIO), Ethernet
- User defined signals

Interoperability guidelines are needed to constrain the configuration, design choices and usage of SpaceVPX, enabling systems that can be composed of modules from different developers

- Ensure that NASA developed modules can be used across multiple missions and applications
- Allow industry to develop SpaceVPX modules that meet NASA mission needs

Other aspects of the SpaceVPX standard present challenges for NASA

- Required redundancy in several areas limits the development of single string systems
- Limits types of fault tolerance architectures and implementations (natively only supports dual redundancy, and does not map directly to other system level fault tolerance patterns)

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NASA SpaceVPX Interoperability Study

- A NASA Engineering & Safety Center (NESC) study was conducted to address the deficiencies in the SpaceVPX standard for NASA missions and define the recommended use of the SpaceVPX standard within NASA

- This study addressed the deficiencies in the SpaceVPX standard for NASA missions enabling interoperability at the card and system level through common functionality, protocols, and physical implementations

- The study team was comprised of subject matter experts across NASA
  - NASA Goddard Space Flight Center (GSFC)
  - NASA Johnson Space Center (JSC)
  - NASA Langley Research Center (LaRC)
  - The Jet Propulsion Laboratory (JPL)
  - *They study team also included a consultant who was key to the development of the original VITA-78 standard*

- The future infusion of NASA's High Performance Spaceflight Computing (HPSC) processor into SpaceVPX systems was a consideration in this study

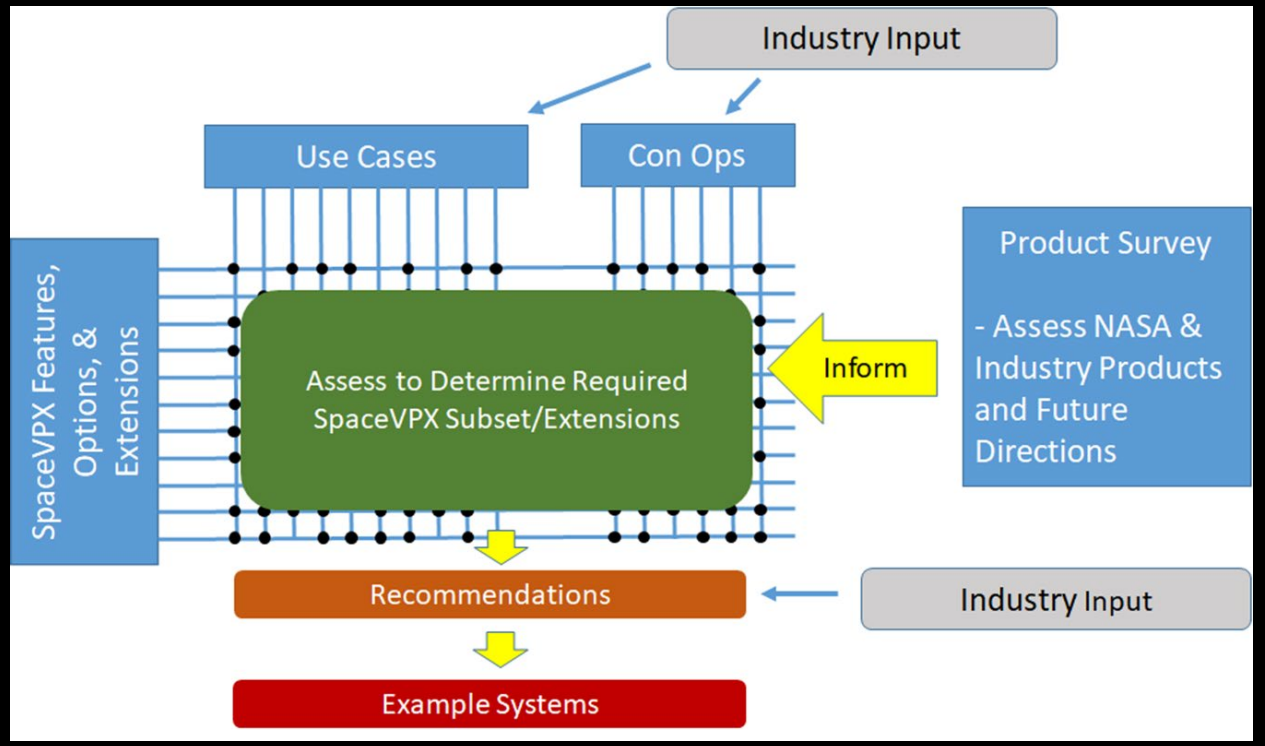
- **The full study report can be found at: https://ntrs.nasa.gov/citations/20220013983**

NASA SpaceVPX Study Approach

The effort was divided into the following tasks:

- Notional use case analysis
- Product surveys
- Study focus area analysis
  - Interconnect
  - Power management and distribution
  - Form factor and daughtercards
  - Fault tolerance
- Engagement with other organizations
- Definition of proposed NASA SpaceVPX specification
- Identification of candidate modules
- Definition of example SpaceVPX systems

Study Approach



Use Case Analysis

Notional use case analysis provided an understanding of the breadth of implementations that SpaceVPX must accommodate and the features, capabilities, and interfaces that are needed to implement a broad range of NASA avionics systems

The following was assessed for each of the12 use cases

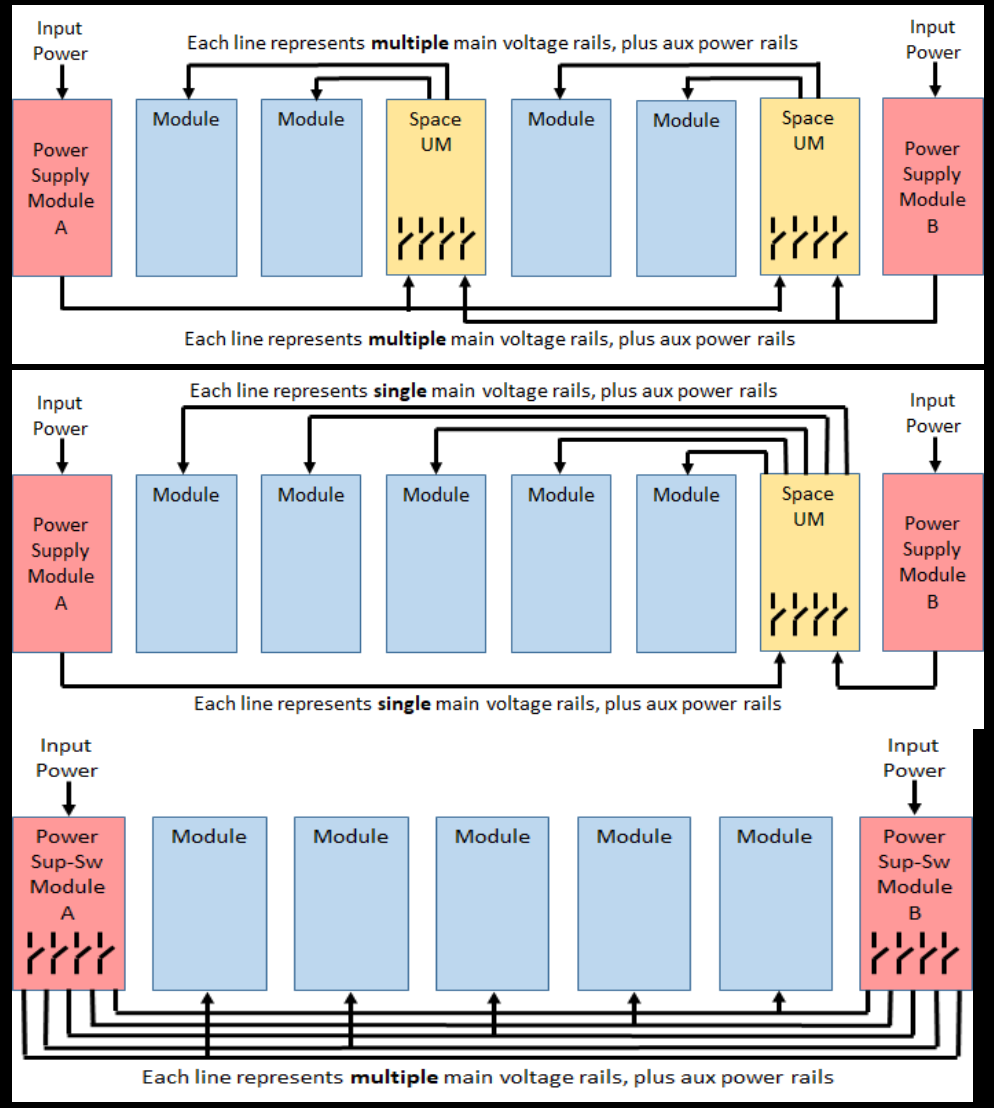
- Orbit / Destination
- Mission Criticality
- SWaP Sensitivity
- Block Diagrams
- Required Interfaces
- Timing and Deterministic Constraints
- Power Architecture
- Redundancy and Fault Management

Notional Use Case	Brief Description
Crewed Mission Avionics (*)	Implementation of Vehicle Control Unit (VCU) and Time Triggered Ethernet (TTE) switch
Crewed Mission Robotics and Surface Vehicle	Implementation of 'Robonaut type' avionics and lunar rover avionics
SmallSat	Combined C&DH and instrument processing in single chassis for an Evolved Secondary Payload Adapter (ESPA) -class mission
On-orbit Servicing, Assembly, and Manufacturing (OSAM)	Implementation of avionics for onboard servicing, assembly, and manufacturing robotics
Science Rover	Robotic science rover avionics
Precision Landing Processor	Implementation of the SPLICE DLC
High Data Rate Missions (3)	High bandwidth Synthetic Aperture Radar (SAR)
	Spectroscopy (based on EMIT mission concept)
	Advanced Earth observing hyperspectral instrument
Low/Medium Data Rate Mission	Generic telescope mission concept with moderate data rates (less than 0.5 Gbps)
Communication Relay Spacecraft	Orbital optical communication relay payload based on Laser Communication Relay Demonstration (LCRD)
HPSC A-Team Use Cases	A hybrid of autonomous planetary mission use cases derived from a JPL HPSC A-Team study

Power Management and Distribution Analysis

- Three power architectures are supported in VITA-78 for 3U systems

Option		Pros	Cons
1	SpaceUM distributes main voltages to two modules (SLT3-SUM-2S3V3A1B1R1M4C-14.7.1)	Compatibility with existing 3U SpaceVPX modules	Most use cases require multiple SpaceUMs, which increases the chassis SWaP
2	SpaceUM distributes one main voltage to 5 modules (SLT3-SUM-5S1V3A1R1M3C-14.7.2)	Limits the number of SpaceUM modules needed	None noted
3	Split SpaceUM function between Power Supply-Switch (SLT3-PSS-6S3V3A1B-14.8.2) and Utility Switch	The use of 2 power supply-switch modules with a utility switch module can reduce the module count for redundant 3U systems	Uncertain that power converters and switches can fit into a single 3U module



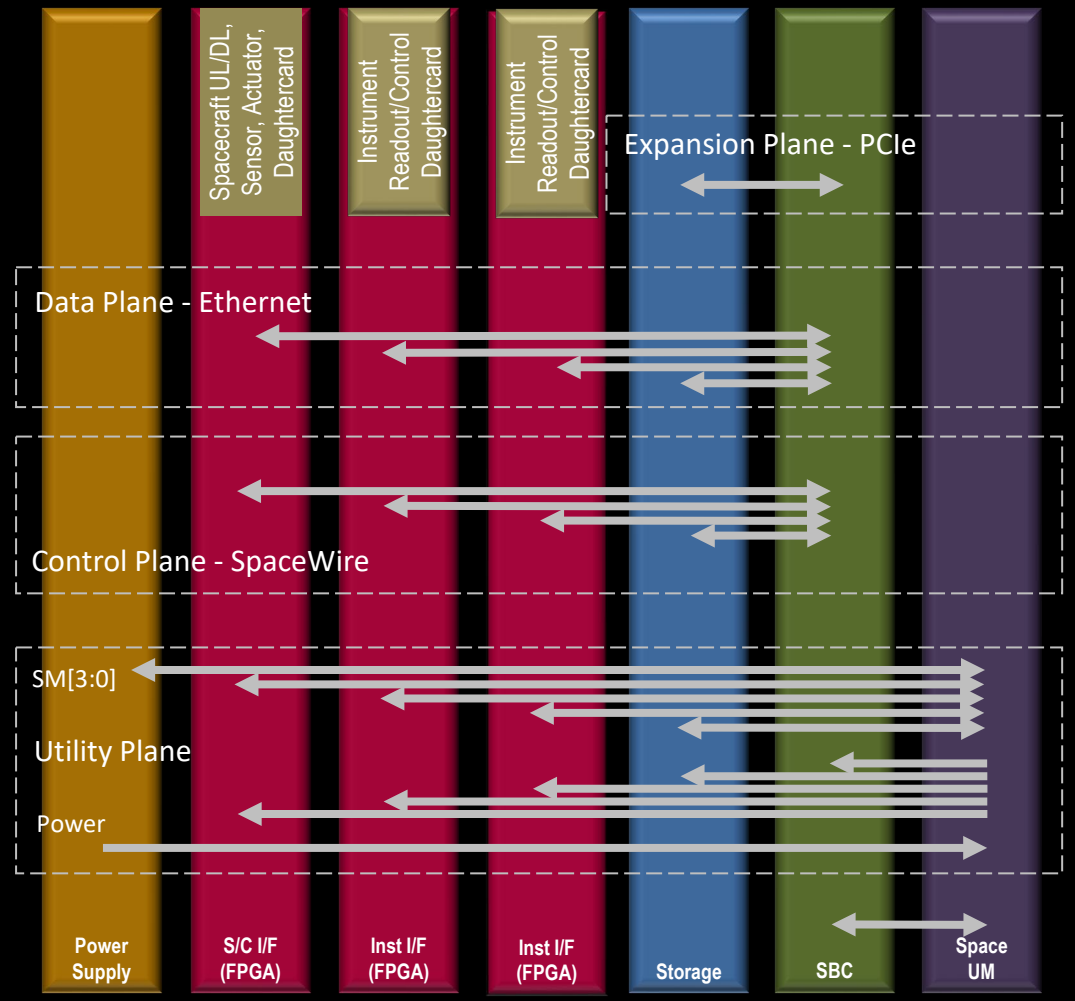
Power Management and Distribution Analysis

- If the 5-output 3U SpaceUM is used, the main power bus voltage must be defined to ensure interoperability.

Option		Pros	Cons	Notes
1	3.3V	Can save voltage regulator, since most NASA systems use 3.3V on a card.	Total chassis power limit may be too low for some applications.	Total primary bus power limited to 120.45W*. Per module primary power limited to 66W*.
2	5V	Adopted by SPLICE.	May be divergent from industry trends.	Total primary bus power limited to 165W. Per module primary power limited to 100W.
3	12V	Consistent with non-aerospace trends. Provides maximum power. However, thermal may be the driving issue for power.	Limited selection of radiation hardened power converters support 12V input.	Total primary bus power limited to 438W. Per module primary power limited to 240W.
* Note that the 3.3V power supply module profile in VITA-62 provides 20A, which would limit total power to 66W.				

Interconnect Analysis

- The SpaceVPX interconnect options outlined in VITA-78 were assessed for the various planes defined in the standard.
- These options were compared the needs of NASA use cases, technology trends within industry, and guidance from SMEs.
- This analysis led to the development of a notional block diagram that illustrates an instrument data system to show the interconnect between modules.
- Note that in determining recommended interconnect standards, the analysis was not bound by the options listed in VITA-78.
- Key interfaces include:
  - Ethernet with support for Time Sensitive Networking (TSN) - TSN is a set of standards that provides bounded latency interconnect for applications requiring determinism, allowing time sensitive messages to be transferred over Ethernet networks
  - PCIe
  - SpaceWire



Single String 3U Smallsat Avionics

Interconnect Analysis

- The High Performance Spaceflight Computing (HPSC) concept study phase significantly influenced the recommendations for SpaceVPX interconnect, and their evaluation of required processor features and interfaces also guided the recommended interconnect standards for the SpaceVPX backplane.
  - The SpaceVPX study also influenced some HPSC requirements.

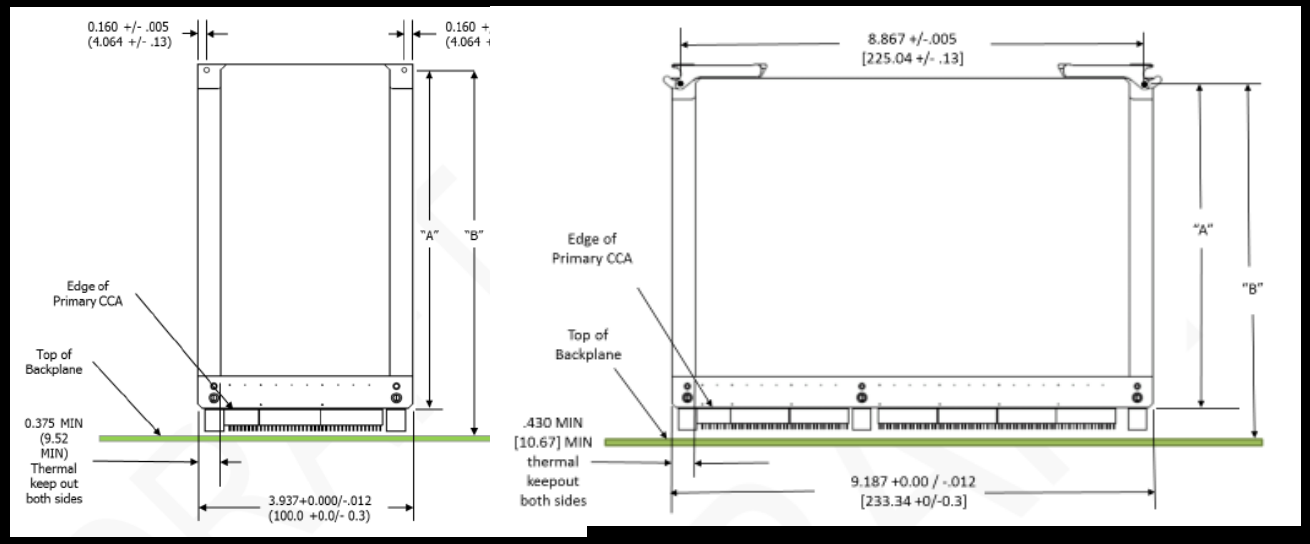
- Key interfaces include:
  - Ethernet with support for Time Sensitive Networking (TSN) - *TSN is a set of standards that provides bounded latency interconnect for applications requiring determinism, allowing time sensitive messages to be transferred over Ethernet networks*
  - PCIe
  - SpaceWire

Interconnect Analysis

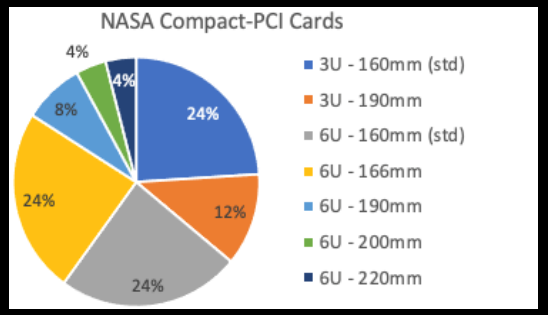
- Interconnect analysis addressed the following topics
  - Optimal interconnect standards for data plane, control plane, utility plane, and expansion plane
  - Additional low-rate interfaces for communication with simple modules
  - JTAG debug and test interface usage
  - Constraints on user defined signals to enable interoperability
  - Support for FPGA programming over the backplane
  - Utilization and allocation of interconnect on 3U and 6U modules
  - The extent to which backplane profiles influence interoperability
  - Signal integrity for high bandwidth signals
  - Backplane connector intermateability

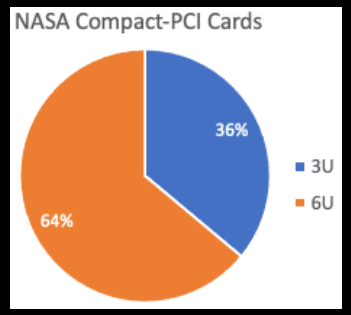
Form Factor and Daughtercard Analysis

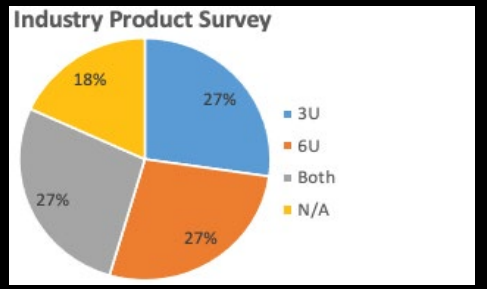
- Previous NASA missions were assessed to determine the module sizes that were used.
- Industry product surveys and use case analysis also provided data on module sizes.
- Current NASA SpaceVPX development is focused on 3U modules with a module length of 220mm.
  - SPLICE (JSC)
  - SpaceCube-V3 (GSFC)

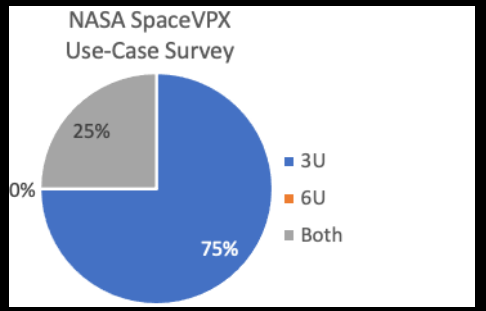


3U and 6U Slot Dimensions [VITA-78]



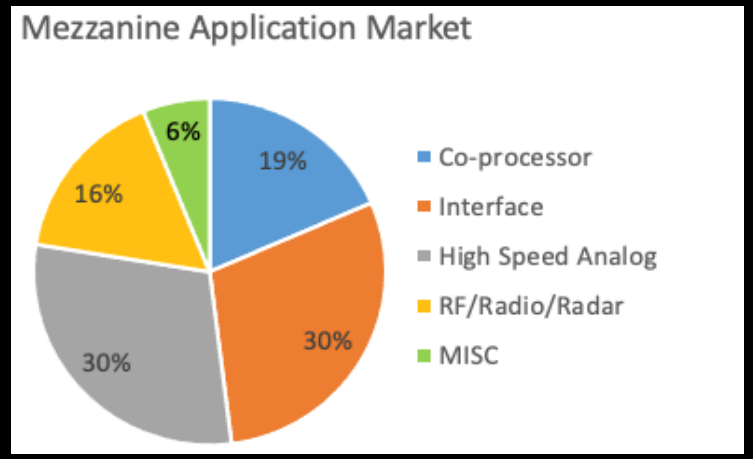


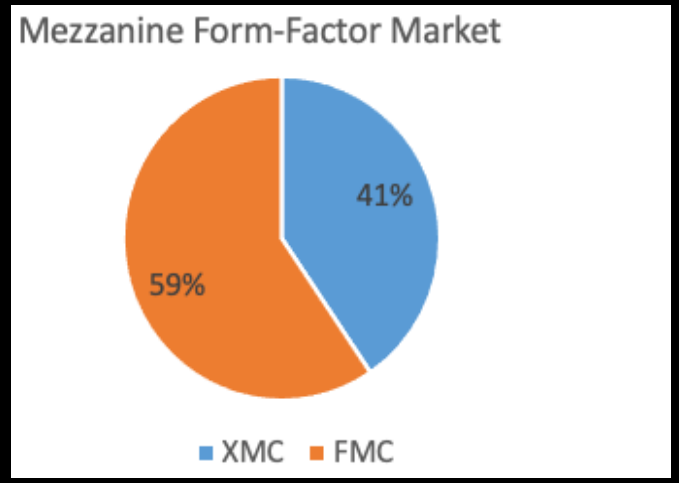




Form Factor and Daughtercard Analysis

- Daughtercards on SpaceVPX modules can provide mission unique functionality and front panel interfaces
- Within industry, the FPGA Mezzanine Card (FMC) [VITA-57.1] and Switched Mezzanine Card (XMC) [VITA-43 and 61] standards are used
- An industry survey assessed to usage and prevalence of each of these standards
- Potential SpaceVPX Daughtercard Configurations
  - A 3U base card is capable of supporting 1 x FMC, or 1 x XMC daughtercard
  - A 6U base card is capable of supporting 3 x FMC, or 2 x XMC daughtercards

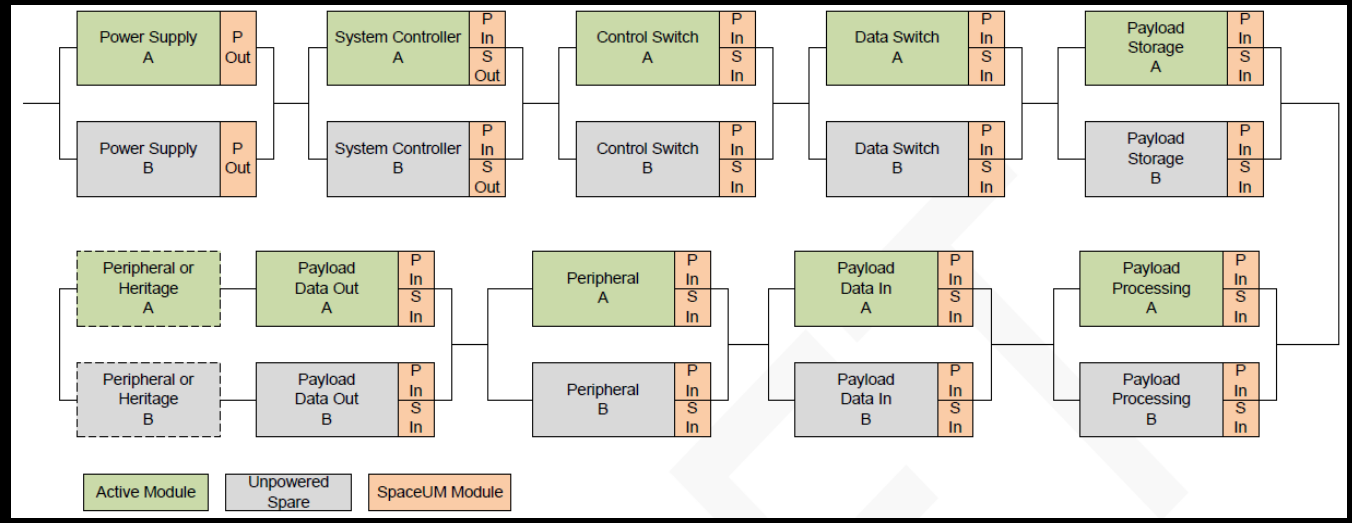




Fault Tolerance Analysis

- Analysis explored the following questions related to SpaceVPX fault tolerance:
  - Are the mechanisms sufficient for use cases?
    - The mechanisms within SpaceVPX that support FDIR and redundancy management are effective building blocks to support all NASA use cases
  - Are they sufficient for mission critical systems (i.e., systems within Class A, human-rated, or high-profile missions)?
    - The VITA-78 standard does not inherently provide the necessary fault detection and isolation required for these applications
    - However, system could potentially be implemented within a single SpaceVPX chassis or across multiple chassis that could provide the necessary fault detection and isolation
  - Are they sufficient for low SWaP constraints?
    - SWaP constrained systems may drive the use of systems on chips (SoC) which can have several redundancy strategies available within a single device
    - For SWaP constrained systems, it is possible that for some missions the desired reliability can be met without invoking the explicit fault tolerance mechanisms defined in SpaceVPX

Fault Tolerance Analysis



- VITA-78 Section 1.7 includes the typical SpaceVPX reliability model diagram
- Since the SpaceUM controls individual power and management signal distribution to the modules, SpaceUM failures can dominate the cut sets for fault tree analysis
- Essentially, a SpaceUM failure results in loss of redundancy

Proposed NASA SpaceVPX Specification

	Proposed NASA Specification
RT-1	**General** Support dual redundant and single string SpaceVPX systems.
RT-2	**Power distribution and management** Utilize the 5-output SpaceUM (SLT3-SUM-5S1V3A1R1M3C-14.7.2) for 3U implementations with a 5V main power voltage. Utilize the 8-output SpaceUM (SLT6-SUM-8S3V3A1B1R1M4C-10.8.1) for 6U implementations with +12, +5, and +3.3 main supply voltages.

RT-3	**Interconnect**
	Support the following interconnect protocols:
	• Data Plane – Support for Ethernet 10GBASE-KR as specified in IEEE 802.3ap with support for TSN as specified in IEEE 802.1AX, CB, AS, Qbv, Qav, Qci, Qcc, and 802.1Q clauses 8.6.5.1 and 8.6.8.2
	• Control Plane - SpaceWire as defined in ECSS-E-ST-50-12C
	• Expansion Plane – JESD204C
	• Expansion Plane – Support for PCIe Gen 3.1
	• Utility Plane – IPMI and DAP as specified in VITA-78
	• User Defined signals with the requirement that they are user programmable
	  • SERDES.- 1600mV peak-to-peak AC-coupled differential signaling; 8b/10b encoding; data rates of 1.25 Gbps, 2.5 Gbps, 3.125 Gbps, 5 Gbps, 6.25 Gbps, and 10 Gbps (note that some modules may not support all of these rates)
	  • Single ended - 2.5V LVCMOS signaling
	• Low-Rate Interconnect – I2C
	• JTAG
	• Provide pin on a front panel to disable JTAG for flight.

Proposed NASA SpaceVPX Specification

	Proposed NASA Specification
RT-4	**Form Factors and Daughtercards** Support 3U and 6U – 220mm form factors. Support for XMC and/or FMC daughtercards on SpaceVPX FPGA-based modules. Combined 3U/6U chassis as needed.
RT-5	**Fault tolerance** Adopt fault tolerance methodologies as defined in VITA-78.
RT-6	**Backplanes and Chassis** Use VITA-78 identified passive backplanes.
RT-7	**Connectors** Utilize SpaceVPX module and backplane that comply with VITA-46.
RT-8	**VITA-78 features not be used to ensure future interoperability** • Specified chassis and backplane profiles. • SRIO on data plane (can be implemented with User Defined SERDES). • SpaceFibre on data plane (can be implemented with User Defined SERDES). • System Controller interfacing to 4 SpaceUM modules (recommendation is 2). • Support for heritage cPCI modules. • Support for 2-output 3U SpaceUM (SLT3-SUM-2S3V3A1B1R1M4C-14.7.1). • Support for VBAT voltage. • System management discrete input and output interfaces. • Full latitude on user defined signal usage .

Proposed NASA SpaceVPX Specification

The following features are proposed that are not currently in VITA-78:

- Explicit support for single string systems
- Using Ethernet/TSN for data plane
- Use of PCIe 3.1 for expansion plane
- JESD-204C support for high bandwidth digitizers
- Constraints on user defined signals
- Explicit daughtercard support

Candidate Module Definitions

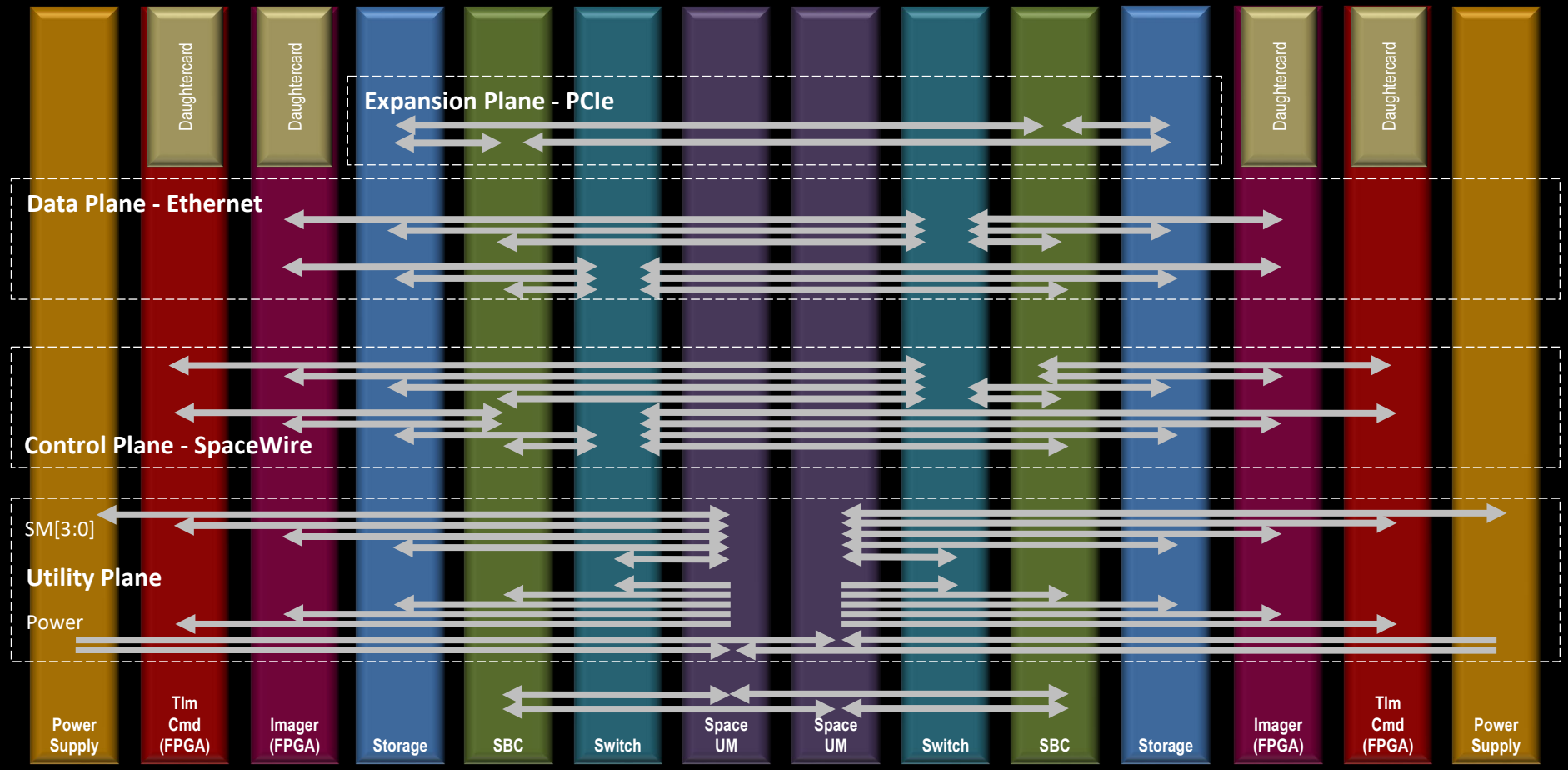
Based on the use cases and the proposed NASA SpaceVPX specification, candidate modules were defined

- Single Board Computer (SBC)
- High Density FPGA
- Low Density FPGA
- Storage
- Digitizer
- Switch

Example Systems

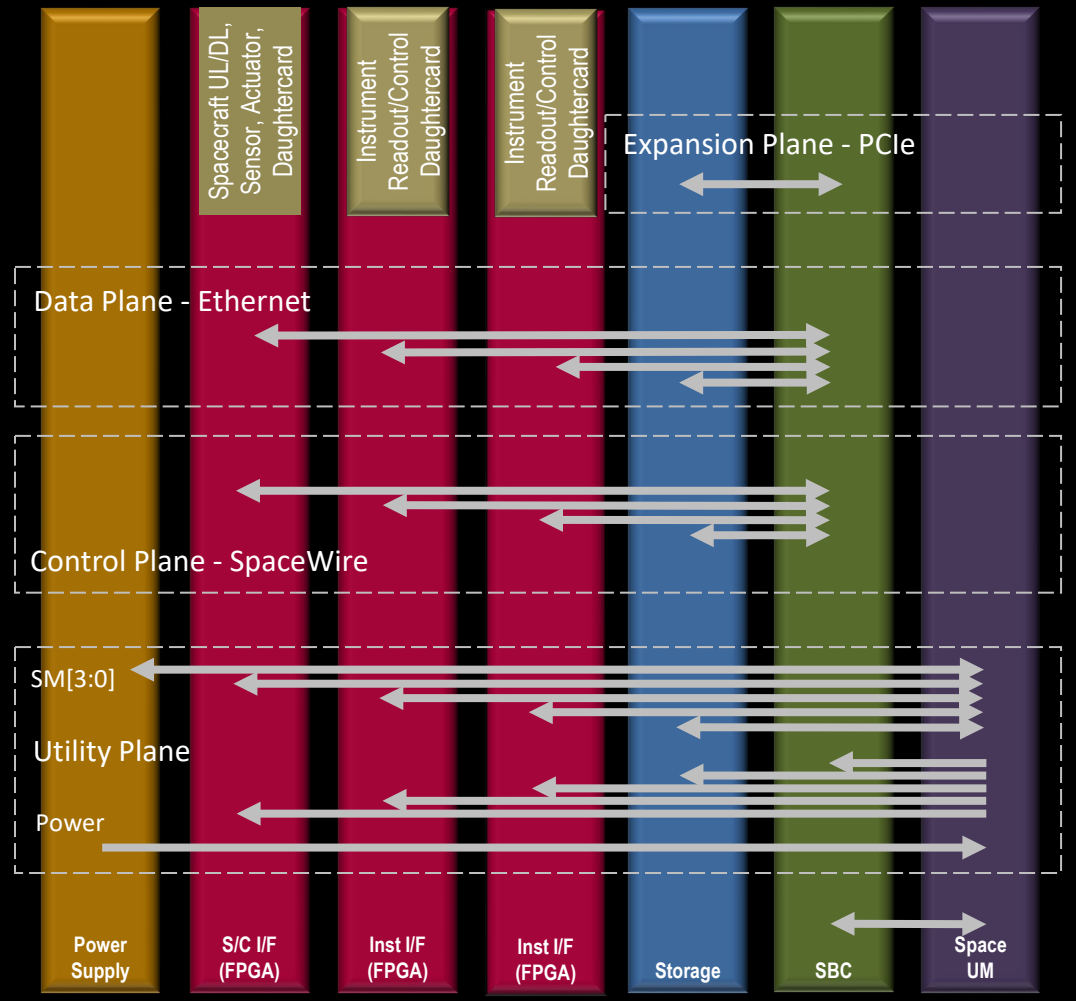
Based on the candidate module definitions and proposed NASA SpaceVPX specification, example systems were defined

- Redundant 3U system
- Single string 3U systems (smallsat avionics, instrument controller)
- Minimalist systems
- Interim systems supporting legacy cPCI modules



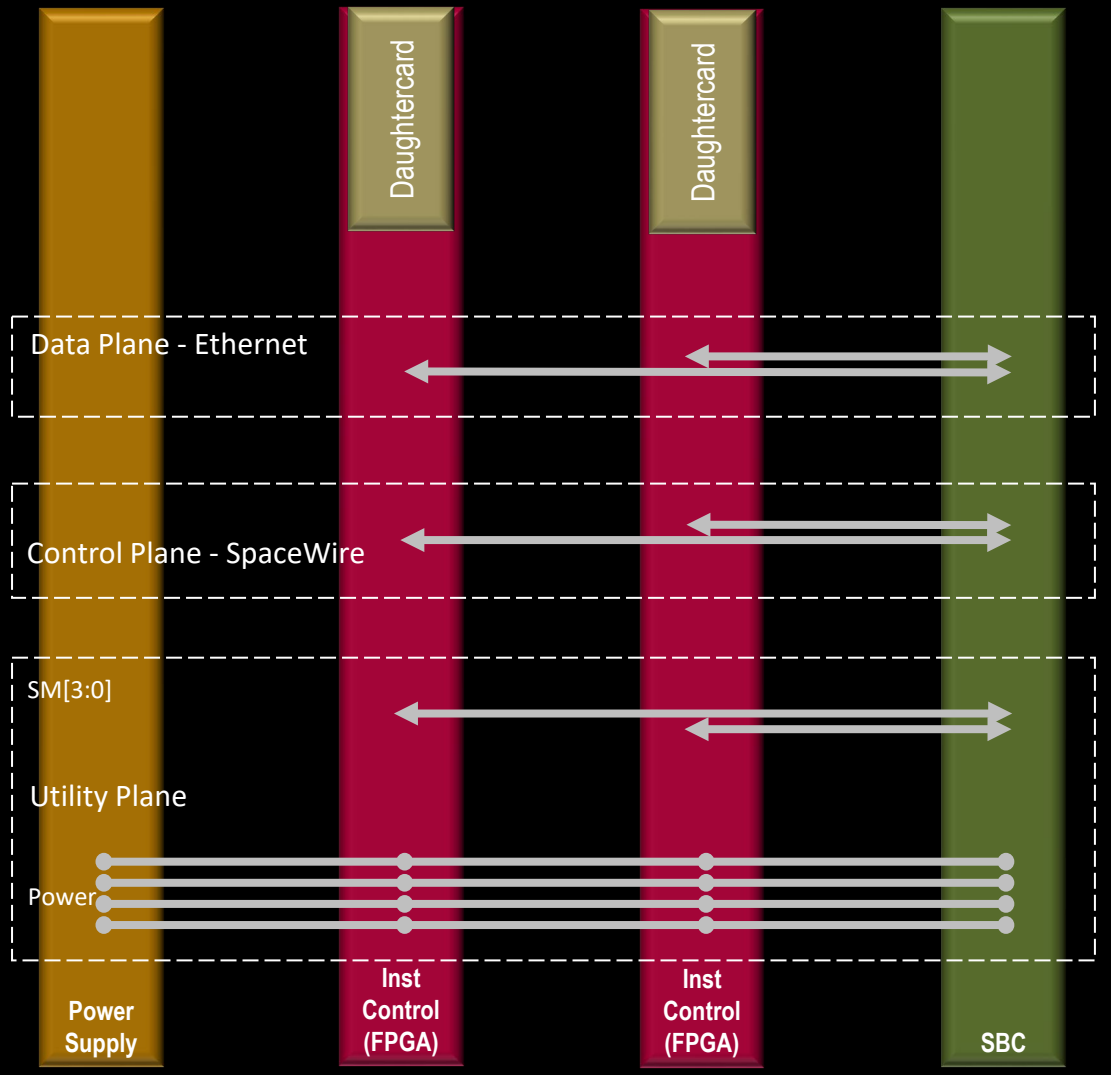
Redundant 3U System

Example Systems



Single String 3U Smallsat Avionics

Example Systems



Minimalist System

In Closing …

- NASA has recently completed a study to assess SpaceVPX interoperability challenges and define a proposed solution
- Using the NASA study recommendations as a starting point for discussion, NASA is engaging with the spaceflight avionics community to develop a SpaceVPX VITA78 ‘dot spec’ that enhances interoperability
- We welcome your input and participation!

Acronym List

AC	Alternating Current	I/O	Intput/Output	POL	Point of Load
cPCI	Compact Peripheral Component Interconnect	JESD	Joint Electron Device Engineering Council Standard	SBC	Single Board Computer
C&DH	Command and Data Handling	JPL	Jet Propulsion Laboratory	SERDES	Serializer Deserializer
DAP	Direct Access Protocol	JTAG	Joint Test Action Group	SPLICE	Safe and Precise Landing – Integrated Capabilities Evolution
DLC	Decent and Landing Computer	LCRD	Laser Communication Relay Demonstration	SRIO	Serial RapidIO
EMIT	Earth Surface Mineral Dust Source Investigation	LEO	Low Earth Orbit	STMD	Space Technology Mission Directorate
ESPA	Evolved Expendable Launch Vehicle (EELV) Secondary Payload Adapter	LVCMOS	Low Voltage Complimentary Oxide Semiconductor	SWaP-C	Size Weight and Power, and Cost
FPGA	Field Programmable Gate Array	mV	Millivolt	TTE	Time Triggered Ethernet
FMC	FPGA Mezzanine Card	NASA	National Aeronautics and Space Administration	TSN	Time-Sensitive Networking
Gbps	Gigabits Per Second	NESC	NASA Engineering & Safety Center	VCU	Vehicle Control Unit
IEEE	Institute of Electrical and Electronics Engineers	OSAM	On-Orbit Servicing Assembly and Manufacturing	VITA	VMEbus (Versa Module Eurocard Bus) International Trade Association
IPMI	Intelligent Platform Management Interface	PCIe	Peripheral Component Interconnect Express	XMC	Express Mezzanine Card